Date: 01.02.2021 **Authorized user: Adrian**

Abazi

Work area: CenTech, **Chemistry Lab** Workplace: CenTech II **Room 2.03**

Safety Instruction Wafer-Saw K&S Model 7100

WWU Münster Nanofabrication Facility (MNF) Center for NanoTechnology (CeNTech) Heisenbergstraße 11 48149 Münster

Range of Application	
Operation Wafer Dicing/Sawing	
Hazard for People and the environment	
 Parts current carrying: possible electrocution risk UV Radiation: possible damage to the eye Possible injuries to limbs/hands due to Moving parts Shattered work piece/wafer Hot components: danger by burn Crushing Hazard 	
Safety Measures and Rules of Behavior	
 Operating the machine is only allowed after previous instructions and knowledge of the manual. Wear adequate personal protective equipment. Perform visual inspection prior to start working. Piping/tubing and connections are to be regularly checked for leaks. Incompatible materials are prohibited. 	
 Keep hands away from process area during cutting/dicing process. Do not touch hot parts or surfaces. 	
Operate machine only with closed lid.	
Action in Failure	
 Push emergency stop Close water supply and compressed air supply Clean machine, secure materials and waste Put machine out of operation Report defects and damages to supervisor Errors are to be resolved only by trained personnel 	
Action in Accident, First Aid	
 Inform appointed first aider. Immediately treat small injuries. Enter data in the accident book. In case of severe injuries call an emergency doctor (phone 112). Inform your superior. 	
Maintenance and Disposal	
 Maintenance work may only be carried out by qualified and instructed staff. Dispose waste in environmentally appropriate manner 	